

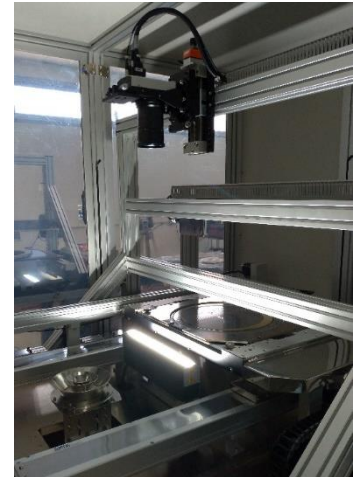
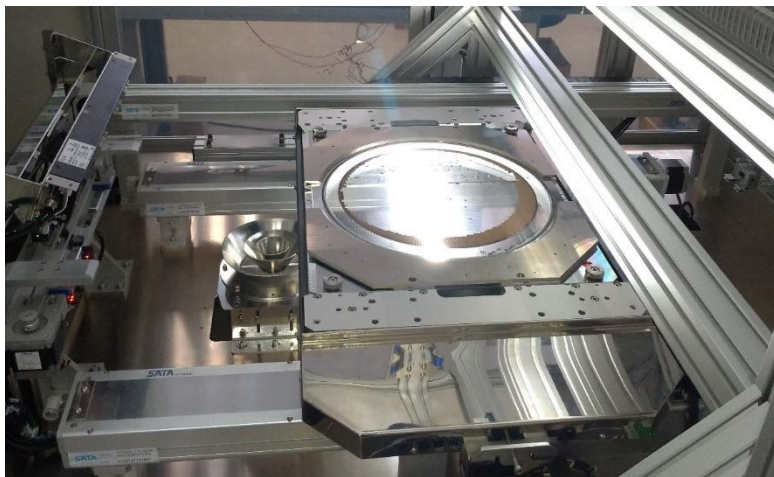
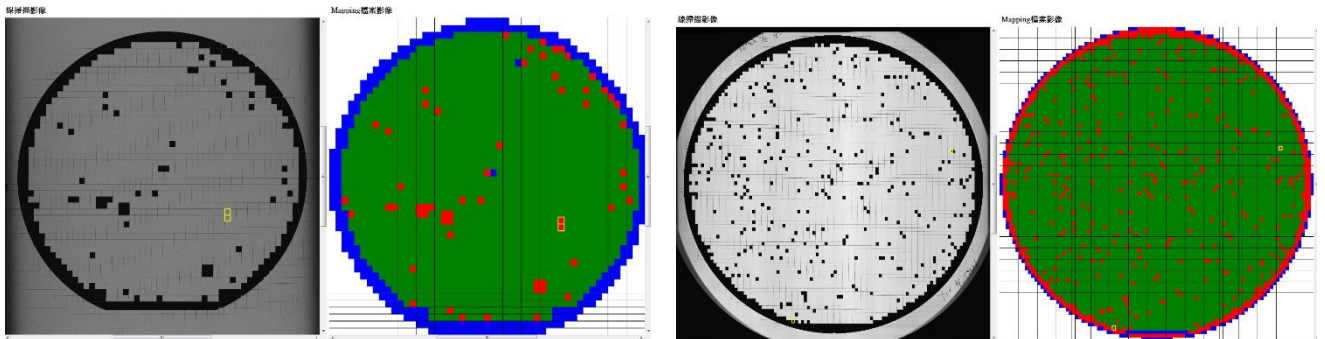
# Hypersonic WS-100

## 晶圓殘料檢測機 (Wafer skeleton inspection)



### Features

- Auto load wafer
- Wafer expansion
- Read wafer ID
- Load wafer mapping data
- Line-scan camera
- Skeleton die inspection
- Analysis and show result
- Mapping rotation is workable
- 8"  $\leftrightarrow$  12" by change kit



<b>WS-100 Specification</b>		
<b>Item</b>	<b>Inspection Module</b>	<b>Specification</b>
1	Vision system	Line-scan camera 16K pixel
2	Light source	Red light
<b>Item</b>	<b>Wafer Handling</b>	
1	Working type	Wafer with frame
2	Wafer size capability	8"; 12"
3	Load port	Single 8" ,12" Framed-wafer cassette
4	Handling	Gripper / Rail
<b>Item</b>	<b>System Dimension</b>	
1	Dimensions (L x W x H)	1500 mm x 1800 mm x 2000 mm
2	Wiegth	1300 Kg